ABSTRACT OF THE DISCLOSURE

The electronic connector (10) includes an improved heat dissipating housing for cooling heat generating devices located within the connector (10). The electronic connector (10) of the present invention enables the cost-effective cooling of electronic devices (22, 24) within the connector (10) while realizing superior thermal conductivity and improved electromagnetic shielding. A method of forming an electronic connector (10) that includes the steps of first providing a heat generating electronic component (22, 24) capable of electronically coupling two data devices together having a first port (16a) and a second port (16b). This component (22, 24) is typically mounted or installed into a circuit board (20). An outer housing (12) of moldable thermally conductive polymer material (102, 202, 302, 402) is overmolded around the heat generating electronic component (22, 24) leaving the first port (16a) and the second port (16b) of connector (10) exposed.